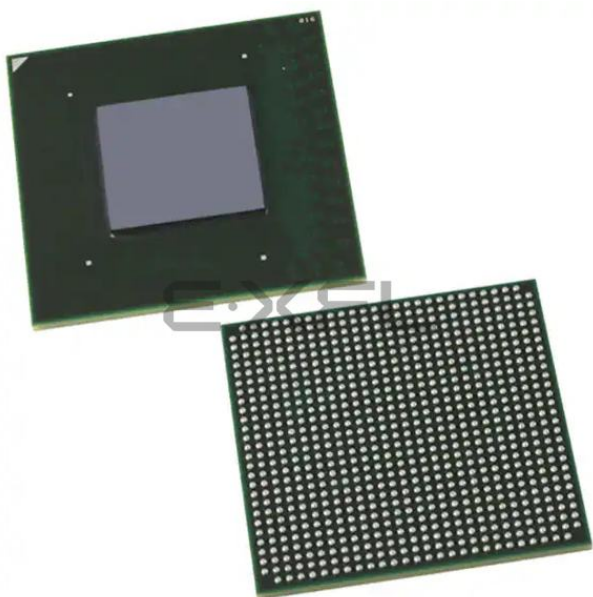




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2530
Number of Logic Elements/Cells	60214
Total RAM Bits	5371904
Number of I/O	364
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx65df29c5

I/O Pin Leakage Current

Table 1-7 lists the Arria II GX I/O pin leakage current specifications.

Table 1-7. I/O Pin Leakage Current for Arria II GX Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-10	—	10	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-10	—	10	μA

Table 1-8 lists the Arria II GZ I/O pin leakage current specifications.

Table 1-8. I/O Pin Leakage Current for Arria II GZ Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-20	—	20	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-20	—	20	μA

Bus Hold

Bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-9 lists bus hold specifications for Arria II GX devices.

Table 1-9. Bus Hold Parameters for Arria II GX Devices (Note 1)

Parameter	Symbol	Cond.	V _{CCIO} (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold low, sustaining current	I _{SUSL}	V _{IN} > V _{IL} (max.)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus-hold high, sustaining current	I _{SUSH}	V _{IN} < V _{IL} (min.)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus-hold low, overdrive current	I _{ODL}	0 V < V _{IN} < V _{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus-hold high, overdrive current	I _{ODH}	0 V < V _{IN} < V _{CCIO}	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA
Bus-hold trip point	V _{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

Note to Table 1-9:

(1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Table 1-11. OCT With and Without Calibration Specification for Arria II GX Device I/Os (Note 1) (Part 2 of 2)

Symbol	Description	Conditions (V)	Calibration Accuracy		Unit
			Commercial	Industrial	
50- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50- Ω series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	%
100- Ω R_D 2.5	100- Ω differential OCT without calibration	$V_{CCIO} = 2.5$	± 30	± 30	%

Note to Table 1-11:

(1) OCT with calibration accuracy is valid at the time of calibration only.

Table 1-12 lists the OCT termination calibration accuracy specifications for Arria II GZ devices.

Table 1-12. OCT with Calibration Accuracy Specifications for Arria II GZ Devices (Note 1)

Symbol	Description	Conditions (V)	Calibration Accuracy			Unit
			C2	C3,I3	C4,I4	
25- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 (2)	25- Ω series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50- Ω internal series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50- Ω R_T 2.5, 1.8, 1.5, 1.2	50- Ω internal parallel OCT with calibration	$V_{CCIO} = 2.5, 1.8,$ 1.5, 1.2	± 10	± 10	± 10	%
20- Ω , 40- Ω , and 60- Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 (3)	20- Ω , 40- Ω and 60- Ω R_S expanded range for internal series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	± 10	%
25- Ω $R_{S_left_shift}$ 3.0, 2.5, 1.8, 1.5, 1.2	25- Ω $R_{S_left_shift}$ internal left shift series OCT with calibration	$V_{CCIO} = 3.0, 2.5,$ 1.8, 1.5, 1.2	± 10	± 10	± 10	%

Notes to Table 1-12:

- (1) OCT calibration accuracy is valid at the time of calibration only.
 (2) 25- Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.
 (3) 20- Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 1-13 lists the Arria II GZ OCT without calibration resistance tolerance to PVT changes.

Table 1-13. OCT Without Calibration Resistance Tolerance Specifications for Arria II GZ Devices

Symbol	Description	Conditions (V)	Resistance Tolerance		Unit
			C3,I3	C4,I4	
25-Ω R _S 3.0 and 2.5	25-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
25-Ω R _S 1.8 and 1.5	25-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
25-Ω R _S 1.2	25-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
50-Ω R _S 3.0 and 2.5	50-Ω internal series OCT without calibration	V _{CCIO} = 3.0, 2.5	± 40	± 40	%
50-Ω R _S 1.8 and 1.5	50-Ω internal series OCT without calibration	V _{CCIO} = 1.8, 1.5	± 40	± 40	%
50-Ω R _S 1.2	50-Ω internal series OCT without calibration	V _{CCIO} = 1.2	± 50	± 50	%
100-Ω R _D 2.5	100-Ω internal differential OCT	V _{CCIO} = 2.5	± 25	± 25	%

OCT calibration is automatically performed at power up for OCT-enabled I/Os. When voltage and temperature conditions change after calibration, the resistance may change. Use Equation 1-1 and Table 1-14 to determine the OCT variation when voltage and temperature vary after power-up calibration for Arria II GX and GZ devices.

Equation 1-1. OCT Variation (Note 1)

$$R_{OCT} = R_{SCAL} \left(1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

Notes to Equation 1-1:

- (1) R_{OCT} value calculated from Equation 1-1 shows the range of OCT resistance with the variation of temperature and V_{CCIO}.

Use the following with Equation 1-1:

- R_{SCAL} is the OCT resistance value at power up.
- ΔT is the variation of temperature with respect to the temperature at power up.
- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

Table 1-14 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GX devices.

Table 1-14. OCT Variation after Power-up Calibration for Arria II GX Devices

Nominal Voltage V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.262	0.035
2.5	0.234	0.039
1.8	0.219	0.086
1.5	0.199	0.136
1.2	0.161	0.288

Table 1-15 lists the OCT variation with temperature and voltage after power-up calibration for Arria II GZ devices.

Table 1-15. OCT Variation after Power-Up Calibration for Arria II GZ Devices (Note 1)

Nominal Voltage, V_{CCIO} (V)	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.189	0.0297
2.5	0.208	0.0344
1.8	0.266	0.0499
1.5	0.273	0.0744
1.2	0.317	0.1241

Note to Table 1-15:

(1) Valid for V_{CCIO} range of $\pm 5\%$ and temperature range of 0° to 85°C.

Pin Capacitance

Table 1-16 lists the pin capacitance for Arria II GX devices.

Table 1-16. Pin Capacitance for Arria II GX Devices

Symbol	Description	Typical	Unit
C_{IO}	Input capacitance on I/O pins, dual-purpose pins (differential I/O, clock, R_{up} , R_{dn}), and dedicated clock input pins	7	pF

Table 1-17 lists the pin capacitance for Arria II GZ devices.

Table 1-17. Pin Capacitance for Arria II GZ Devices

Symbol	Description	Typical	Unit
C_{IOTB}	Input capacitance on the top and bottom I/O pins	4	pF
C_{IOLR}	Input capacitance on the left and right I/O pins	4	pF
C_{CLKTB}	Input capacitance on the top and bottom non-dedicated clock input pins	4	pF
C_{CLKLR}	Input capacitance on the left and right non-dedicated clock input pins	4	pF
C_{OUTFB}	Input capacitance on the dual-purpose clock output and feedback pins	5	pF
C_{CLK1} , C_{CLK3} , C_{CLK8} , and C_{CLK10}	Input capacitance for dedicated clock input pins	2	pF

Internal Weak Pull-Up and Weak Pull-Down Resistors

Table 1-18 lists the weak pull-up and pull-down resistor values for Arria II GX devices.

Table 1-18. Internal Weak Pull-up and Weak Pull-Down Resistors for Arria II GX Devices (Note 1)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R_{PU}	Value of I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	$V_{CCIO} = 3.3 \text{ V} \pm 5\%$ (2)	7	25	41	k Ω
		$V_{CCIO} = 3.0 \text{ V} \pm 5\%$ (2)	7	28	47	k Ω
		$V_{CCIO} = 2.5 \text{ V} \pm 5\%$ (2)	8	35	61	k Ω
		$V_{CCIO} = 1.8 \text{ V} \pm 5\%$ (2)	10	57	108	k Ω
		$V_{CCIO} = 1.5 \text{ V} \pm 5\%$ (2)	13	82	163	k Ω
		$V_{CCIO} = 1.2 \text{ V} \pm 5\%$ (2)	19	143	351	k Ω
R_{PD}	Value of TCK pin pull-down resistor	$V_{CCIO} = 3.3 \text{ V} \pm 5\%$	6	19	29	k Ω
		$V_{CCIO} = 3.0 \text{ V} \pm 5\%$	6	22	32	k Ω
		$V_{CCIO} = 2.5 \text{ V} \pm 5\%$	6	25	42	k Ω
		$V_{CCIO} = 1.8 \text{ V} \pm 5\%$	7	35	70	k Ω
		$V_{CCIO} = 1.5 \text{ V} \pm 5\%$	8	50	112	k Ω

Notes to Table 1-18:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.
- (2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .

Table 1-19 lists the weak pull-up resistor values for Arria II GZ devices.

Table 1-19. Internal Weak Pull-Up Resistor for Arria II GZ Devices (Note 1), (2)

Symbol	Description	Conditions	Min	Typ	Max	Unit
R _{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if the programmable pull-up resistor option is enabled.	V _{CCIO} = 3.0 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 2.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.8 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.5 V ±5% (3)	—	25	—	kΩ
		V _{CCIO} = 1.2 V ±5% (3)	—	25	—	kΩ

Notes to Table 1-19:

- (1) All I/O pins have an option to enable weak pull-up except configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.
- (3) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

Hot Socketing

Table 1-20 lists the hot-socketing specification for Arria II GX and GZ devices.

Table 1-20. Hot Socketing Specifications for Arria II Devices

Symbol	Description	Maximum
I _{IOPIN(DC)}	DC current per I/O pin	300 μA
I _{IOPIN(AC)}	AC current per I/O pin	8 mA (1)
I _{XCVRTX(DC)}	DC current per transceiver TX pin	100 mA
I _{XCVRRX(DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-20:

- (1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |I_{IOPIN}| = C dv/dt, in which “C” is I/O pin capacitance and “dv/dt” is slew rate.

Schmitt Trigger Input

The Arria II GX device supports Schmitt trigger input on the TDI, TMS, TCK, nSTATUS, nCONFIG, nCE, CONF_DONE, and DCLK pins. A Schmitt trigger feature introduces hysteresis to the input signal for improved noise immunity, especially for signals with slow edge rates.

Table 1-21 lists the hysteresis specifications across the supported V_{CCIO} range for Schmitt trigger inputs in Arria II GX devices.

Table 1-21. Schmitt Trigger Input Hysteresis Specifications for Arria II GX Devices

Symbol	Description	Condition (V)	Minimum	Unit
V _{Schmitt}	Hysteresis for Schmitt trigger input	V _{CCIO} = 3.3	220	mV
		V _{CCIO} = 2.5	180	mV
		V _{CCIO} = 1.8	110	mV
		V _{CCIO} = 1.5	70	mV

Table 1–33 lists the differential I/O standard specifications for Arria II GZ devices.

Table 1–33. Differential I/O Standard Specifications for Arria II GZ Devices (Note 1)

I/O Standard (2)	V _{CCIO} (V)			V _{ID} (mV)			V _{ICM(DC)} (V)		V _{OD} (V) (3)			V _{OCM} (V) (3)		
	Min	Typ	Max	Min	Cond.	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
2.5 V LVDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1.125	1.25	1.375
2.5 V LVDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1	1.25	1.5
RSDS (HIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.4
RSDS (VIO)	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.5
Mini-LVDS (HIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.4
Mini-LVDS (VIO)	2.375	2.5	2.625	200	—	600	0.4	1.32 5	0.25	—	0.6	1	1.2	1.5
LVPECL	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
BLVDS (4)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—

Notes to Table 1–33:

- (1) 1.4-V/1.5-V PCML transceiver I/O standard specifications are described in “Transceiver Performance Specifications” on page 1–21.
- (2) Vertical I/O (VIO) is top and bottom I/Os; horizontal I/O (HIO) is left and right I/Os.
- (3) R_L range: 90 ≤ R_L ≤ 110 Ω.
- (4) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. These specifications depend on the system topology.

Power Consumption for the Arria II Device Family

Altera offers two ways to estimate power for a design:

- Using the Microsoft Excel-based Early Power Estimator
- Using the Quartus® II PowerPlay Power Analyzer feature

The interactive Microsoft Excel-based Early Power Estimator is typically used prior to designing the FPGA in order to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities which, when combined with detailed circuit models, can yield very accurate power estimates.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Table 1–34. Transceiver Specifications for Arria II GX Devices (Note 1) (Part 2 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	—	100	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	1100 $\pm$ 5%			1100 $\pm$ 5%			1100 $\pm$ 5%			1100 $\pm$ 5%			mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	$\geq$ 1 MHz	—	—	-130	—	—	-130	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK (3)	10 KHz to 20 MHz	—	—	3	—	—	3	—	—	3	—	—	3	ps
R_{ref}	—	—	2000 $\pm$ 1%	—	—	2000 $\pm$ 1%	—	—	2000 $\pm$ 1%	—	—	2000 $\pm$ 1%	—	Ω
Transceiver Clocks														
Calibration block clock frequency (cal_blk_clk)	—	10	—	125	10	—	125	10	—	125	10	—	125	MHz

Table 1-35. Transceiver Specifications for Arria II GZ Devices (Part 2 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Transceiver Clocks								
Calibration block clock frequency (cal_blk_clk)	—	10	—	125	10	—	125	MHz
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
reconfig_clk clock frequency	Dynamic reconfiguration clock frequency	2.5/ 37.5 (4)	—	50	2.5/ 37.5 (4)	—	50	MHz
Delta time between reconfig_clks (5)	—	—	—	2	—	—	2	ms
Transceiver block minimum power-down (gxb_powerdown) pulse width	—	1	—	—	1	—	—	μs
Receiver								
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Data rate (16)	—	600	—	6375	600	—	3750	Mbps
Absolute V _{MAX} for a receiver pin (6)	—	—	—	1.6	—	—	1.6	V
Operational V _{MAX} for a receiver pin	—	—	—	1.5	—	—	1.5	V
Absolute V _{MIN} for a receiver pin	—	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration	V _{ICM} = 0.82 V setting	—	—	2.7	—	—	2.7	V
	V _{ICM} = 1.1 V setting (7)	—	—	1.6	—	—	1.6	V
Minimum differential eye opening at receiver serial input pins (8)	Data Rate = 600 Mbps to 5 Gbps Equalization = 0 DC gain = 0 dB	100	—	—	165	—	—	mV
	Data Rate > 5 Gbps Equalization = 0 DC gain = 0 dB	165	—	—	165	—	—	mV
V _{ICM}	V _{ICM} = 0.82 V setting	820 ± 10%			820 ± 10%			mV
	V _{ICM} = 1.1 V setting (7)	1100 ± 10%			1100 ± 10%			mV

Table 1-35. Transceiver Specifications for Arria II GZ Devices (Part 3 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Receiver DC Coupling Support	—	For more information about receiver DC coupling support, refer to the “DC-Coupled Links” section in the <i>Transceiver Architecture for Arria II Devices</i> chapter.						
Differential on-chip termination resistors	85–Ω setting	85 ± 20%			85 ± 20%			Ω
	100–Ω setting	100 ± 20%			100 ± 20%			Ω
	120–Ω setting	120 ± 20%			120 ± 20%			Ω
	150–Ω setting	150 ± 20%			150 ± 20%			Ω
Differential and common mode return loss	PCIe (Gen 1 and Gen 2), XAUI, HiGig+, CEI SR/LR, SRIO SR/LR, CPRI LV/HV, OBSAI, SATA	Compliant						—
Programmable PPM detector (9)	—	± 62.5, 100, 125, 200, 250, 300, 500, 1,000						ppm
Run length	—	—	—	200	—	—	200	UI
Programmable equalization	—	—	—	16	—	—	16	dB
t _{LTR} (10)	—	—	—	75	—	—	75	μs
t _{LTR_LTD_Manual} (11)	—	15	—	—	15	—	—	μs
t _{LTD_Manual} (12)	—	—	—	4000	—	—	4000	ns
t _{LTD_Auto} (13)	—	—	—	4000	—	—	4000	ns
Receiver CDR 3 dB Bandwidth in lock-to-data (LTD) mode	PCIe Gen1	2.0 - 3.5						MHz
	PCIe Gen2	40 - 65						MHz
	(OIF) CEI PHY at 6.375 Gbps	20 - 35						MHz
	XAUI	10 - 18						MHz
	SRIO 1.25 Gbps	10 - 18						MHz
	SRIO 2.5 Gbps	10 - 18						MHz
	SRIO 3.125 Gbps	6 - 10						MHz
	GIGE	6 - 10						MHz
	SONET OC12	3 - 6						MHz
	SONET OC48	14 - 19						MHz
Receiver buffer and CDR offset cancellation time (per channel)	—	—	—	17000	—	—	17000	recon fig_ clk cycles
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	dB

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 4 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Transmitter								
Supported I/O Standards	1.5-V PCML							
Data rate (14)	—	600	—	6375	600	—	3750	Mbps
V _{OCM}	0.65 V setting	—	650	—	—	650	—	mV
Differential on-chip termination resistors	85–Ω setting	85 ± 15%			85 ± 15%			Ω
	100–Ω setting	100 ± 15%			100 ± 15%			Ω
	120–Ω setting	120 ± 15%			120 ± 15%			Ω
	150–Ω setting	150 ± 15%			150 ± 15%			Ω
Differential and common mode return loss	PCIe Gen1 and Gen2 (TX V _{OD} =4), XAUI (TX V _{OD} =6), HiGig+ (TX V _{OD} =6), CEI SR/LR (TX V _{OD} =8), SRIO SR (V _{OD} =6), SRIO LR (V _{OD} =8), CPRI LV (V _{OD} =6), CPRI HV (V _{OD} =2), OBSAI (V _{OD} =6), SATA (V _{OD} =4),	Compliant						—
Rise time (15)	—	50	—	200	50	—	200	ps
Fall time (15)	—	50	—	200	50	—	200	ps
Intra-differential pair skew	—	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to-channel skew	×4 PMA and PCS bonded mode Example: XAUI, PCIe ×4, Basic ×4	—	—	120	—	—	120	ps
Inter-transceiver block transmitter channel-to-channel skew	×8 PMA and PCS bonded mode Example: PCIe ×8, Basic ×8	—	—	500	—	—	500	ps
CMU0 PLL and CMU1 PLL								
Supported Data Range	—	600	—	6375	600	—	3750	Mbps
pll_powerdown minimum pulse width (tp _{pll_powerdown})	—	1			1			μs
CMU PLL lock time from pll_powerdown de-assertion	—	—	—	100	—	—	100	μs

Table 1–39 lists typical transmitter pre-emphasis levels for Arria II GZ devices (in dB) for the first post tap under the following conditions (low-frequency data pattern [five 1s and five 0s] at 6.25 Gbps). The levels listed in Table 1–39 are a representation of possible pre-emphasis levels under the specified conditions only and that the pre-emphasis levels may change with data pattern and data rate.



To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the [Arria II HSSI HSPICE](#) models.

Table 1–39. Transmitter Pre-Emphasis Levels for Arria II GZ Devices (Part 1 of 2)

Pre-Emphasis 1st Post-Tap Setting	V _{DD} Setting							
	0	1	2	3	4	5	6	7
0	0	0	0	0	0	0	0	0
1	N/A	0.7	0	0	0	0	0	0
2	N/A	1	0.3	0	0	0	0	0
3	N/A	1.5	0.6	0	0	0	0	0
4	N/A	2	0.7	0.3	0	0	0	0
5	N/A	2.7	1.2	0.5	0.3	0	0	0
6	N/A	3.1	1.3	0.8	0.5	0.2	0	0
7	N/A	3.7	1.8	1.1	0.7	0.4	0.2	0
8	N/A	4.2	2.1	1.3	0.9	0.6	0.3	0
9	N/A	4.9	2.4	1.6	1.2	0.8	0.5	0.2
10	N/A	5.4	2.8	1.9	1.4	1	0.7	0.3
11	N/A	6	3.2	2.2	1.7	1.2	0.9	0.4
12	N/A	6.8	3.5	2.6	1.9	1.4	1.1	0.6
13	N/A	7.5	3.8	2.8	2.1	1.6	1.2	0.6
14	N/A	8.1	4.2	3.1	2.3	1.7	1.3	0.7
15	N/A	8.8	4.5	3.4	2.6	1.9	1.5	0.8
16	N/A	N/A	4.9	3.7	2.9	2.2	1.7	0.9
17	N/A	N/A	5.3	4	3.1	2.4	1.8	1.1
18	N/A	N/A	5.7	4.4	3.4	2.6	2	1.2
19	N/A	N/A	6.1	4.7	3.6	2.8	2.2	1.4
20	N/A	N/A	6.6	5.1	4	3.1	2.4	1.5
21	N/A	N/A	7	5.4	4.3	3.3	2.7	1.7
22	N/A	N/A	8	6.1	4.8	3.8	3	2
23	N/A	N/A	9	6.8	5.4	4.3	3.4	2.3
24	N/A	N/A	10	7.6	6	4.8	3.9	2.6
25	N/A	N/A	11.4	8.4	6.8	5.4	4.4	3
26	N/A	N/A	12.6	9.4	7.4	5.9	4.9	3.3
27	N/A	N/A	N/A	10.3	8.1	6.4	5.3	3.6
28	N/A	N/A	N/A	11.3	8.8	7.1	5.8	4

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (Note 1) (Part 3 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
PCIe Receiver Jitter Tolerance (4)														
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			> 0.6			> 0.6			UI
PCIe (Gen 1) Electrical Idle Detect Threshold (9)														
VRX-IDLE-DETDIFF (p-p)	Compliance pattern	65	—	175	65	—	175	65	—	175	65	—	175	mV
Serial RapidIO® (SRIO) Transmit Jitter Generation (5)														
Deterministic jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
Total jitter (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
SRIO Receiver Jitter Tolerance (5)														
Deterministic jitter tolerance (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data Rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 1.875 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
	Jitter frequency = 20 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI
GIGE Transmit Jitter Generation (6)														
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	—	—	0.14	—	—	0.14	UI

Table 1-41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 4 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
GIGE Receiver Jitter Tolerance (11)								
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.4			> 0.4			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.66			> 0.66			UI
HiGig Transmit Jitter Generation								
Deterministic jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.17	—	—	—	UI
Total jitter (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	—	—	0.35	—	—	—	UI
HiGig Receiver Jitter Tolerance								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	> 0.37			—	—	—	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 3.75 Gbps Pattern = CJPAT	> 0.65			—	—	—	UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT	> 8.5			—	—	—	UI
	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT	> 0.1			—	—	—	UI
	Jitter frequency = 22.1 KHz Data rate = 3.75 Gbps Pattern = CJPAT	> 0.1			—	—	—	UI
(OIF) CEI Transmitter Jitter Generation								
Total jitter (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS15 BER = 10 ⁻¹²	—	—	0.3	—	—	0.3	UI
(OIF) CEI Receiver Jitter Tolerance								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.675			—	—	—	UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.988			—	—	—	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 5 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter Frequency = 38.2 KHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.5			—	—	—	UI
	Jitter Frequency = 3.82 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
	Jitter Frequency = 20 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10 ⁻¹²	> 0.05			—	—	—	UI
SDI Transmitter Jitter Generation (12)								
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) Pattern = color bar Low-frequency roll-off = 100 KHz	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) Pattern = color bar Low-frequency roll-off = 100 KHz	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (12)								
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) pattern = 75% color bar	> 1			> 1			UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
SAS Transmit Jitter Generation (13)								
Total jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 6 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Deterministic jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.25	—	—	0.25	UI
Random jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.15	—	—	0.15	UI
SAS Receiver Jitter Tolerance (13)								
Total jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.65	—	—	0.65	UI
Deterministic jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Sinusoidal jitter tolerance at 1.5 Gbps (G1)	Jitter frequency = 900 KHz to 5 MHz Pattern = CJTPAT BER = 1E-12	> 0.1			> 0.1			UI
CPRI Transmit Jitter Generation (14)								
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance (14)								
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.65			> 0.65			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation (15)								
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 MBps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.17	—	—	0.17	UI

Table 1-45. PLL Specifications for Arria II GZ Devices (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
f_{CLBW}	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth (7)	—	4	—	MHz
$t_{\text{PLL_PSERR}}$	Accuracy of PLL phase shift	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the areset signal	10	—	—	ns
t_{INCCJ} (3), (4)	Input clock cycle to cycle jitter ($F_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle to cycle jitter ($F_{\text{REF}} < 100$ MHz)	—	—	±750	ps (p-p)
$t_{\text{OUTPJ_DC}}$ (5)	Period Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTCCJ_DC}}$ (5)	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle to Cycle Jitter for dedicated clock output ($F_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{OUTPJ_IO}}$ (5), (8)	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ_IO}}$ (5), (8)	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle to Cycle Jitter for clock output on regular I/O ($F_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC_OUTPJ_DC}}$ (5), (6)	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} \geq 100$ MHz)	—	—	250	ps (p-p)
	Period Jitter for dedicated clock output in cascaded PLLs ($F_{\text{OUT}} < 100$ MHz)	—	—	25	mUI (p-p)
f_{DRIFT}	Frequency drift after PFDENA is disabled for duration of 100 μ s	—	—	±10	%

Notes to Table 1-45:

- (1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (2) This specification is limited by the lower of the two: I/O F_{MAX} or F_{OUT} of the PLL.
- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 120 ps.
- (4) F_{REF} is f_{IN}/N when $N = 1$.
- (5) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in [Table 1-64 on page 1-71](#).
- (6) The cascaded PLL specification is only applicable with the following condition:
 - a. Upstream PLL: $0.59 \text{ MHz} \leq \text{Upstream PLL BW} < 1 \text{ MHz}$
 - b. Downstream PLL: $\text{Downstream PLL BW} > 2 \text{ MHz}$
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) External memory interface clock output jitter specifications use a different measurement method, which is available in [Table 1-63 on page 1-71](#).

Configuration

Table 1–50 lists the configuration mode specifications for Arria II GX and GZ devices.

Table 1–50. Configuration Mode Specifications for Arria II Devices

Programming Mode	DCLK Frequency			Unit
	Min	Typ	Max	
Passive serial	—	—	125	MHz
Fast passive parallel	—	—	125	MHz
Fast active serial (fast clock)	17	26	40	MHz
Fast active serial (slow clock)	8.5	13	20	MHz
Remote update only in fast AS mode	—	—	10	MHz

JTAG Specifications

Table 1–51 lists the JTAG timing parameters and values for Arria II GX and GZ devices.

Table 1–51. JTAG Timing Parameters and Values for Arria II Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU(TDI)}$	TDI JTAG port setup time	1	—	ns
$t_{JPSU(TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	11	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14	ns

Chip-Wide Reset (Dev_CLRn) Specifications

Table 1–52 lists the specifications for the chip-wide reset (Dev_CLRn) for Arria II GX and GZ devices.

Table 1–52. Chip-Wide Reset (Dev_CLRn) Specifications for Arria II Devices

Description	Min	Typ	Max	Unit
Dev_CLRn	500	—	—	μs

Table 1-53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - f_{HSDRPA} (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1–60 lists the DQS phase shift error for Arria II GX devices.

Table 1–60. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria II GX Devices (Note 1)

Number of DQS Delay Buffer	C4	I3, C5, I5	C6	Unit
1	26	30	36	ps
2	52	60	72	ps
3	78	90	108	ps
4	104	120	144	ps

Note to Table 1–60:

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a C4 speed grade is ± 78 ps or ± 39 ps.

Table 1–61 lists the DQS phase shift error for Arria II GZ devices.

Table 1–61. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Arria II GZ Devices (Note 1)

Number of DQS Delay Buffer	–3	–4	Unit
1	28	30	ps
2	56	60	ps
3	84	90	ps
4	112	120	ps

Note to Table 1–61:

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a 3 speed grade is ± 84 ps or ± 42 ps.

Table 1–62 lists the memory output clock jitter specifications for Arria II GX devices.

Table 1–62. Memory Output Clock Jitter Specification for Arria II GX Devices (Note 1), (2), (3)

Parameter	Clock Network	Symbol	–4		–5		–6		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	Global	$t_{JIT(per)}$	-100	100	-125	125	-125	125	ps
Cycle-to-cycle period jitter	Global	$t_{JIT(cc)}$	-200	200	-250	250	-250	250	ps
Duty cycle jitter	Global	$t_{JIT(duty)}$	-100	100	-125	125	-125	125	ps

Notes to Table 1–62:

- (1) The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.
- (2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock network.
- (3) The memory output clock jitter stated in Table 1–62 is applicable when an input jitter of 30 ps is applied.